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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	4848
Number of Logic Elements/Cells	43632
Total RAM Bits	3538944
Number of I/O	804
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1148-BBGA, FCBGA
Supplier Device Package	1148-FCPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp40-6ff1148i

- HSTL (1.5V and 1.8V, Class I, II, III, and IV)
- SSTL (1.8V and 2.5V, Class I and II)

The DCI I/O feature automatically provides on-chip termination for each single-ended I/O standard.

The IOB elements also support the following differential signaling I/O standards:

- LVDS and Extended LVDS (2.5V)
- BLVDS (Bus LVDS)
- ULVDS
- LDT
- LVPECL (2.5V)

Two adjacent pads are used for each differential pair. Two or four IOBs connect to one switch matrix to access the routing resources. On-chip differential termination is available for LVDS, LVDS Extended, ULVDS, and LDT standards.

Configurable Logic Blocks (CLBs)

CLB resources include four slices and two 3-state buffers. Each slice is equivalent and contains:

- Two function generators (F & G)
- Two storage elements
- Arithmetic logic gates
- Large multiplexers
- Wide function capability
- Fast carry look-ahead chain
- Horizontal cascade chain (OR gate)

The function generators F & G are configurable as 4-input look-up tables (LUTs), as 16-bit shift registers, or as 16-bit distributed SelectRAM+ memory.

In addition, the two storage elements are either edge-triggered D-type flip-flops or level-sensitive latches.

Each CLB has internal fast interconnect and connects to a switch matrix to access general routing resources.

Block SelectRAM+ Memory

The block SelectRAM+ memory resources are 18 Kb of True Dual-Port RAM, programmable from 16K x 1 bit to 512 x 36 bit, in various depth and width configurations. Each port is totally synchronous and independent, offering three "read-during-write" modes. Block SelectRAM+ memory is cascadable to implement large embedded storage blocks. Supported memory configurations for dual-port and single-port modes are shown in Table 2.

Table 2: **Dual-Port and Single-Port Configurations**

16K x 1 bit	4K x 4 bits	1K x 18 bits
8K x 2 bits	2K x 9 bits	512 x 36 bits

18 X 18 Bit Multipliers

A multiplier block is associated with each SelectRAM+ memory block. The multiplier block is a dedicated 18 x 18-bit 2s complement signed multiplier, and is optimized for operations based on the block SelectRAM+ content on one port. The 18 x 18 multiplier can be used independently of the block SelectRAM+ resource. Read/multiply/accumulate operations and DSP filter structures are extremely efficient.

Both the SelectRAM+ memory and the multiplier resource are connected to four switch matrices to access the general routing resources.

Global Clocking

The DCM and global clock multiplexer buffers provide a complete solution for designing high-speed clock schemes.

Up to twelve DCM blocks are available. To generate deskewed internal or external clocks, each DCM can be used to eliminate clock distribution delay. The DCM also provides 90-, 180-, and 270-degree phase-shifted versions of its output clocks. Fine-grained phase shifting offers high-resolution phase adjustments in increments of $^{1}/_{256}$ of the clock period. Very flexible frequency synthesis provides a clock output frequency equal to a fractional or integer multiple of the input clock frequency. For exact timing parameters, see Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics.

Virtex-II Pro devices have 16 global clock MUX buffers, with up to eight clock nets per quadrant. Each clock MUX buffer can select one of the two clock inputs and switch glitch-free from one clock to the other. Each DCM can send up to four of its clock outputs to global clock buffers on the same edge. Any global clock pin can drive any DCM on the same edge.

Routing Resources

The IOB, CLB, block SelectRAM+, multiplier, and DCM elements all use the same interconnect scheme and the same access to the global routing matrix. Timing models are shared, greatly improving the predictability of the performance of high-speed designs.

There are a total of 16 global clock lines, with eight available per quadrant. In addition, 24 vertical and horizontal long lines per row or column, as well as massive secondary and local routing resources, provide fast interconnect. Virtex-II Pro buffered interconnects are relatively unaffected by net fanout, and the interconnect layout is designed to minimize crosstalk.

Horizontal and vertical routing resources for each row or column include:

- 24 long lines
- 120 hex lines
- 40 double lines
- 16 direct connect lines (total in all four directions)

Boundary Scan

Boundary-scan instructions and associated data registers support a standard methodology for accessing and configuring Virtex-II Pro devices, complying with IEEE standards 1149.1 and 1532. A system mode and a test mode are

Virtex-II Pro / Virtex-II Pro X Device/Package Combinations and Maximum I/Os

Offerings include ball grid array (BGA) packages with 1.0 mm pitch. In addition to traditional wire-bond interconnect (FG/FGG packages), flip-chip interconnect (FF packages) is used in some of the BGA offerings. Flip-chip interconnect construction supports more I/Os than are possible in wire-bond versions of similar packages, providing a high pin count and excellent power dissipation.

The device/package combination table (Table 3) details the maximum number of user I/Os and RocketIO / RocketIO X MGTs for each device and package using wire-bond or flip-chip technology.

The FF1148 and FF1696 packages have no RocketIO transceivers bonded out. Extra SelectIO-Ultra resources occupy available pins in these packages, resulting in a higher user I/O count. These packages are available for the XC2VP40, XC2VP50, and XC2VP100 devices only.

The I/Os per package count includes all user I/Os except the 15 control pins (CCLK, DONE, M0, M1, M2, PROG_B, PWRDWN_B, TCK, TDI, TDO, TMS, HSWAP_EN, DXN, DXP, and RSVD), VBATT, and the RocketIO / RocketIO X transceiver pins.

Table 3: **Virtex-II Pro Device/Package Combinations and Maximum Number of Available I/Os**

Package(1)	FG256/ FGG256	FG456/ FGG456	FG676	FF672	FF896	FF1152	FF1148	FF1517	FF1704	FF1696
Pitch (mm)	**1.00**	**1.00**	**1.00**	**1.00**	**1.00**	**1.00**	**1.00**	**1.00**	**1.00**	**1.00**
Size (mm)	**17 x 17**	**23 x 23**	**26 x 26**	**27 x 27**	**31 x 31**	**35 x 35**	**35 x 35**	**40 x 40**	**42.5 x 42.5**	**42.5 x 42.5**
XC2VP2	140 / 4	156 / 4		204 / 4						
XC2VP4	140 / 4	248 / 4		348 / 4						
XC2VP7		248 / 8		396 / 8	396 / 8					
XC2VP20			404 / 8		556 / 8	564 / 8				
XC2VPX20					552 / 8(2)					
XC2VP30			416 / 8		556 / 8	644 / 8				
XC2VP40			416 / 8			692 / 12	804 / 0(3)			
XC2VP50						692 / 16	812 / 0(3)	852 / 16		
XC2VP70								964 / 16	996 / 20	
XC2VPX70									992 / 20(2)	
XC2VP100									1,040 / 20	1,164 / 0(3)

Notes:
1. Wirebond packages FG256, FG456, and FG676 are also available in Pb-free versions FGG256, FGG456, and FGG676. See Virtex-II Pro Ordering Examples for details on how to order.
2. Virtex-II Pro X device is equipped with RocketIO X transceiver cores.
3. The RocketIO transceivers in devices in the FF1148 and FF1696 packages are not bonded out to the package pins.

Maximum Performance

Maximum performance of the RocketIO / RocketIO X transceiver and the PowerPC processor block varies, depending on package style and speed grade. See Table 4 for details. Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics contains the rest of the FPGA fabric performance parameters.

Table 4: **Maximum RocketIO / RocketIO X Transceiver and Processor Block Performance**

Device	Speed Grade			Units
	-7(1)	-6	-5	
RocketIO X Transceiver FlipChip (FF)	N/A	6.25(3)	4.25(3)	Gb/s
RocketIO Transceiver FlipChip (FF)	3.125	3.125	2.0	Gb/s
RocketIO Transceiver Wirebond (FG)	2.5	2.5	2.0	Gb/s
PowerPC Processor Block	400(2)	350(2)	300	MHz

Notes:
1. -7 speed grade devices are not available in Industrial grade.
2. **IMPORTANT!** When CPMC405CLOCK runs at speeds greater than 350 MHz in -7 Commercial grade dual-processor devices, or greater than 300 MHz in -6 Industrial grade dual-processor devices, users must implement the technology presented in **XAPP755**, "PowerPC 405 Clock Macro for -7(C) and -6(I) Speed Grade Dual-Processor Devices." Refer to Table 1 to identify dual-processor devices.
3. XC2VPX70 is only available at fixed 4.25 Gb/s baud rate.

CRC may adjust certain trailing bytes to generate the required running disparity at the end of the packet.

On the receiver side, the CRC logic verifies the received CRC value, supporting the same standards as above.

The CRC logic also supports a user mode, with a simple data packet stucture beginning and ending with user-defined SOP and EOP characters.

Loopback

In order to facilitate testing without having the need to either apply patterns or measure data at GHz rates, two programmable loop-back features are available.

One option, serial loopback, places the gigabit transceiver into a state where transmit data is directly fed back to the receiver. An important point to note is that the feedback path is at the output pads of the transmitter. This tests the entirety of the transmitter and receiver.

The second option, parallel loopback, checks the digital circuitry. When parallel loopback is enabled, the serial loopback path is disabled. However, the transmitter outputs remain active, and data can be transmitted. If TXINHIBIT is asserted, TXP is forced to 0 until TXINHIBIT is de-asserted.

Reset

The receiver and transmitter have their own synchronous reset inputs. The transmitter reset recenters the transmission FIFO, and resets all transmitter registers and the 8B/10B decoder. The receiver reset recenters the receiver elastic buffer, and resets all receiver registers and the 8B/10B encoder. Neither reset has any effect on the PLLs.

Power

All RocketIO transceivers in the FPGA, whether instantiated in the design or not, must be connected to power and ground. Unused transceivers can be powered by any 2.5V source, and passive filtering is not required.

Power Down

The Power Down module is controlled by the transceiver's POWERDOWN input pin. The Power Down pin on the FPGA package has no effect on the transceiver.

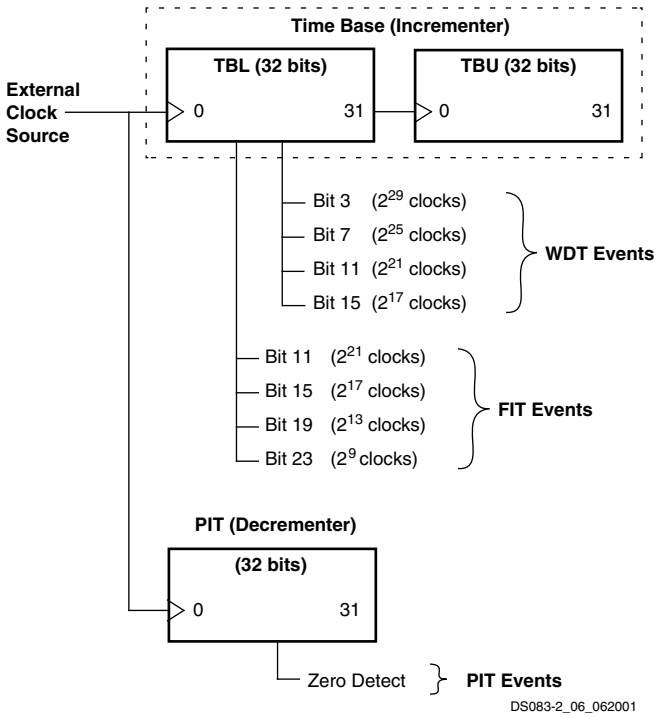

Figure 17: **Relationship of Timer Facilities to Base Clock**

Interrupts

The PPC405 provides an interface to an interrupt controller that is logically outside the PPC405 core. This controller combines the asynchronous interrupt inputs and presents them to the embedded core as a single interrupt signal. The sources of asynchronous interrupts are external signals, the JTAG/debug unit, and any implemented peripherals.

Debug Logic

All architected resources on the embedded PPC405 core can be accessed through the debug logic. Upon a debug event, the PPC405 core provides debug information to an external debug tool. Three different types of tools are supported depending on the debug mode: ROM monitors, JTAG debuggers, and instruction trace tools.

In internal debug mode, a debug event enables exception-handling software at a dedicated interrupt vector to take over the CPU core and communicate with a debug tool. The debug tool has read-write access to all registers and can set hardware or software breakpoints. ROM monitors typically use the internal debug mode.

In external debug mode, the CPU core enters stop state (stops instruction execution) when a debug event occurs. This mode offers a debug tool read-write access to all registers in the PPC405 core. Once the CPU core is in stop state, the debug tool can start the CPU core, step an instruction, freeze the timers, or set hardware or software break points. In addition to CPU core control, the debug logic is capable of writing instructions into the instruction cache, eliminating the need for external memory during initial board bring-up. Communication to a debug tool using external debug mode is through the JTAG port.

Debug wait mode offers the same functionality as external debug mode with one exception. In debug wait mode, the CPU core goes into wait state instead of stop state after a debug event. Wait state is identical to stop state until an interrupt occurs. In wait state, the PPC405 core can vector to an exception handler, service an interrupt and return to wait state. This mode is particularly useful when debugging real time control systems.

Real-time trace debug mode is always enabled. The debug logic continuously broadcasts instruction trace information to the trace port. When a debug event occurs, the debug logic signals an external debug tool to save instruction trace information before and after the event. The number of instructions traced depends on the trace tool.

Debug events signal the debug logic to stop the CPU core, put the CPU core in debug wait state, cause a debug exception or save instruction trace information.

Big Endian and Little Endian Support

The embedded PPC405 core supports big endian or little endian byte ordering for instructions stored in external memory. Since the PowerPC architecture is big endian internally, the ICU rearranges the instructions stored as little endian into the big endian format. Therefore, the instruction cache always contains instructions in big endian format so that the byte ordering is correct for the execution unit. This feature allows the 405 core to be used in systems designed to function in a little endian environment.

Figure 57 shows clock distribution in Virtex-II Pro devices.

In each quadrant, up to eight clocks are organized in clock rows. A clock row supports up to 16 CLB rows (eight up and eight down). To reduce power consumption, any unused clock branches remain static.

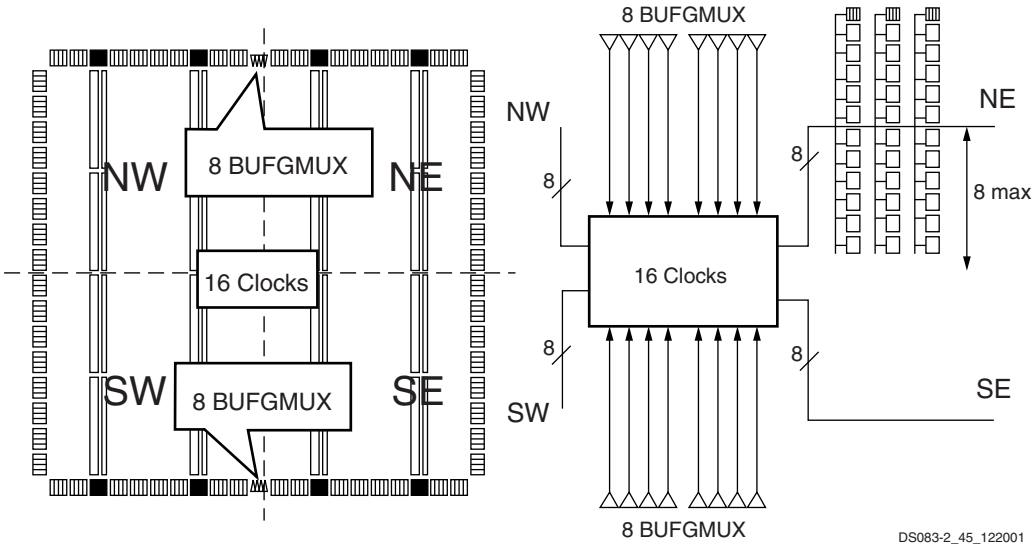

Figure 57: **Virtex-II Pro Clock Distribution**

Global clocks are driven by dedicated clock buffers (BUFG), which can also be used to gate the clock (BUFGCE) or to multiplex between two independent clock inputs (BUFGMUX).

The most common configuration option of this element is as a buffer. A BUFG function in this (global buffer) mode, is shown in Figure 58.

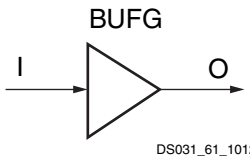

Figure 58: **Virtex-II Pro BUFG Function**

The Virtex-II Pro global clock buffer BUFG can also be configured as a clock enable/disable circuit (Figure 59), as well as a two-input clock multiplexer (Figure 60). A functional description of these two options is provided below. Each of them can be used in either of two modes, selected by configuration: rising clock edge or falling clock edge.

This section describes the rising clock edge option. For the opposite option, falling clock edge, just change all "rising" references to "falling" and all "High" references to "Low", except for the description of the CE and S levels. The rising clock edge option uses the BUFGCE and BUFGMUX primitives. The falling clock edge option uses the BUFGCE_1 and BUFGMUX_1 primitives.

BUFGCE

If the CE input is active (High) prior to the incoming rising clock edge, this Low-to-High-to-Low clock pulse passes through the clock buffer. Any level change of CE during the incoming clock High time has no effect.

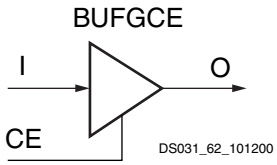

Figure 59: **Virtex-II Pro BUFGCE Function**

If the CE input is inactive (Low) prior to the incoming rising clock edge, the following clock pulse does not pass through the clock buffer, and the output stays Low. Any level change of CE during the incoming clock High time has no effect. CE must not change during a short setup window just prior to the rising clock edge on the BUFGCE input I. Violating this setup time requirement can result in an undefined runt pulse output.

BUFGMUX

BUFGMUX can switch between two unrelated, even asynchronous clocks. Basically, a Low on S selects the I_0 input, a High on S selects the I_1 input. Switching from one clock to the other is done in such a way that the output High and Low time is never shorter than the shortest High or Low time of either input clock. As long as the presently selected clock is High, any level change of S has no effect.

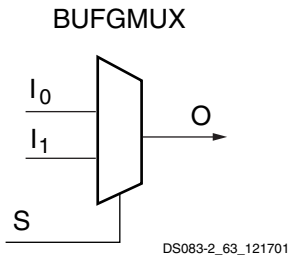

Figure 60: **Virtex-II Pro BUFGMUX Function**

If the presently selected clock is Low while S changes, or if it goes Low after S has changed, the output is kept Low until the other ("to-be-selected") clock has made a transition from High to Low. At that instant, the new clock starts driving the output.

The two clock inputs can be asynchronous with regard to each other, and the S input can change at any time, except for a short setup time prior to the rising edge of the presently selected clock (I0 or I1). Violating this setup time requirement can result in an undefined runt pulse output.

All Virtex-II Pro devices have 16 global clock multiplexer buffers.

Figure 61 shows a switchover from I0 to I1.

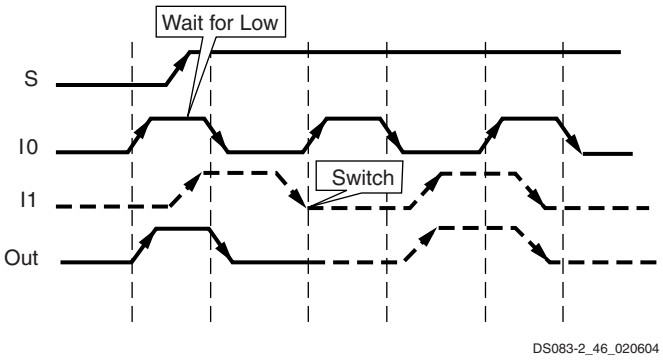

Figure 61: **Clock Multiplexer Waveform Diagram**

- The current clock is CLK0.
- S is activated High.
- If CLK0 is currently High, the multiplexer waits for CLK0 to go Low.
- Once CLK0 is Low, the multiplexer output stays Low until CLK1 transitions High to Low.
- When CLK1 transitions from High to Low, the output switches to CLK1.
- No glitches or short pulses can appear on the output.

Local Clocking

In addition to global clocks, there are local clock resources in the Virtex-II Pro devices. There are more than 72 local clocks in the Virtex-II Pro family. These resources can be used for many different applications, including but not limited to memory interfaces. For example, even using only the left and right I/O banks, Virtex-II Pro FPGAs can support up to 50 local clocks for DDR SDRAM. These interfaces can operate beyond 200 MHz on Virtex-II Pro devices.

Digital Clock Manager (DCM)

The Virtex-II Pro DCM offers a wide range of powerful clock management features.

- **Clock De-skew**: The DCM generates new system clocks (either internally or externally to the FPGA), which are phase-aligned to the input clock, thus eliminating clock distribution delays.
- **Frequency Synthesis**: The DCM generates a wide range of output clock frequencies, performing very flexible clock multiplication and division.
- **Phase Shifting**: The DCM provides both coarse phase shifting and fine-grained phase shifting with dynamic phase shift control.

The DCM utilizes fully digital delay lines allowing robust high-precision control of clock phase and frequency. It also utilizes fully digital feedback systems, operating dynamically to compensate for temperature and voltage variations during operation.

Up to four of the nine DCM clock outputs can drive inputs to global clock buffers or global clock multiplexer buffers simultaneously (see Figure 62). All DCM clock outputs can simultaneously drive general routing resources, including routes to output buffers.

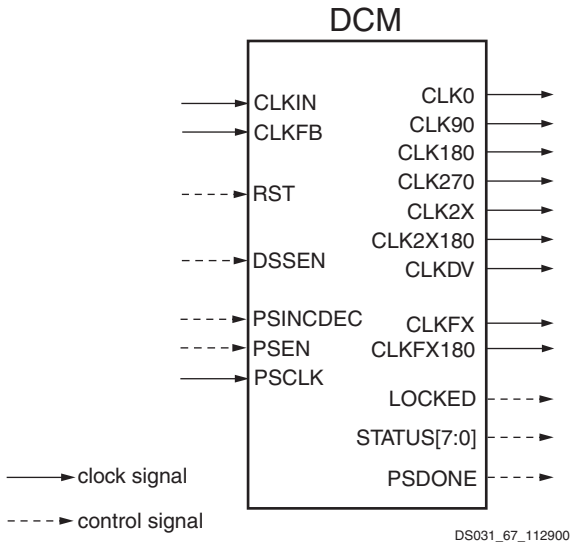

Figure 62: **Digital Clock Manager**

The DCM can be configured to delay the completion of the Virtex-II Pro configuration process until after the DCM has achieved lock. This guarantees that the chip does not begin operating until after the system clocks generated by the DCM have stabilized.

Table 65: **Package Skew**

Description	Symbol	Device/Package	Value	Units
Package Skew(1)	$T_{PKGSKEW}$	XC2VP2FF672	104	ps
		XC2VP4FF672	102	ps
		XC2VP7FF672	92	ps
		XC2VP7FF896	101	ps
		XC2VP20FF896	93	ps
		XC2VPX20FF896	93	ps
		XC2VP20FF1152	106	ps
		XC2VP30FF896	86	ps
		XC2VP30FF1152	112	ps
		XC2VP40FF1152	92	ps
		XC2VP40FF1148	100	ps
		XC2VP50FF1152	88	ps
		XC2VP50FF1148	101	ps
		XC2VP50FF1517	97	ps
		XC2VP70FF1517	95	ps
		XC2VP70FF1704	101	ps
		XC2VPX70FF1704	101	ps
		XC2VP100FF1704	86	ps
		XC2VP100FF1696	100	ps

Notes:
1. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball (7.1ps per mm).
2. Package trace length information is available for these device/package combinations. This information can be used to deskew the package.

Table 66: **Sample Window**

Description	Symbol	Device	Speed Grade			Units
			–7	–6	–5	
Sampling Error at Receiver Pins(1)	T_{SAMP}	All	0.50	0.50	0.50	ns

Notes:
1. This parameter indicates the total sampling error of Virtex-II Pro DDR input registers across voltage, temperature, and process. The characterization methodology uses the DCM to capture the DDR input registers' edges of operation.
2. These measurements include:
   - CLK0 and CLK180 DCM jitter
   - Worst-case duty-cycle distortion, T_{DCD_CLK180}
   - DCM accuracy (phase offset)
   - DCM phase shift resolution

   These measurements do not include package or clock tree skew.

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
3	IO_L49N_3	T22	NC		
3	IO_L49P_3	T21	NC		
3	IO_L48N_3	T20	NC		
3	IO_L48P_3	T19	NC		
3	IO_L47N_3	T18	NC		
3	IO_L47P_3	U18	NC		
3	IO_L45N_3/VREF_3	U22	NC		
3	IO_L45P_3	U21	NC		
3	IO_L43N_3	U20	NC		
3	IO_L43P_3	U19	NC		
3	IO_L06N_3	V22			
3	IO_L06P_3	V21			
3	IO_L05N_3	V20			
3	IO_L05P_3	V19			
3	IO_L03N_3/VREF_3	W22			
3	IO_L03P_3	W21			
3	IO_L02N_3	Y22			
3	IO_L02P_3	Y21			
3	IO_L01N_3/VRP_3	AA22			
3	IO_L01P_3/VRN_3	AB21			
4	IO_L01N_4/BUSY/DOUT(1)	W18			
4	IO_L01P_4/INIT_B	W17			
4	IO_L02N_4/D0/DIN(1)	V17			
4	IO_L02P_4/D1	V16			
4	IO_L03N_4/D2	W16			
4	IO_L03P_4/D3	Y16			
4	IO_L05_4/No_Pair	V15			
4	IO_L06N_4/VRP_4	W15			
4	IO_L06P_4/VRN_4	Y15			
4	IO_L07N_4	U14			
4	IO_L07P_4/VREF_4	V14			
4	IO_L09N_4	W14			
4	IO_L09P_4/VREF_4	W13			
4	IO_L67N_4	U13			
4	IO_L67P_4	V13			
4	IO_L69N_4	Y13			

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	IO_L88N_7/VREF_7	L5			
7	IO_L86P_7	L6			
7	IO_L86N_7	K6			
7	IO_L85P_7	K1			
7	IO_L85N_7	K2			
7	IO_L60P_7	K3	NC		
7	IO_L60N_7	K4	NC		
7	IO_L58P_7	K5	NC		
7	IO_L58N_7/VREF_7	J5	NC		
7	IO_L56P_7	J1	NC		
7	IO_L56N_7	J2	NC		
7	IO_L55P_7	J3	NC		
7	IO_L55N_7	J4	NC		
7	IO_L54P_7	J6	NC		
7	IO_L54N_7	H5	NC		
7	IO_L52P_7	H1	NC		
7	IO_L52N_7/VREF_7	H2	NC		
7	IO_L50P_7	H3	NC		
7	IO_L50N_7	H4	NC		
7	IO_L49P_7	G1	NC		
7	IO_L49N_7	G2	NC		
7	IO_L48P_7	G3	NC		
7	IO_L48N_7	G4	NC		
7	IO_L46P_7	G5	NC		
7	IO_L46N_7/VREF_7	F5	NC		
7	IO_L43P_7	F1	NC		
7	IO_L43N_7	F2	NC		
7	IO_L06P_7	F3			
7	IO_L06N_7	F4			
7	IO_L04P_7	E1			
7	IO_L04N_7/VREF_7	E2			
7	IO_L03P_7	E3			
7	IO_L03N_7	E4			
7	IO_L02P_7	D1			
7	IO_L02N_7	D2			
7	IO_L01P_7/VRN_7	C1			
7	IO_L01N_7/VRP_7	C2			

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	AVCCAUXTX18	AA14			
N/A	AVCCAUXRX19	AA10			
N/A	VTRXPAD19	AA9			
N/A	RXNPAD19	AB10			
N/A	RXPPAD19	AB9			
N/A	GNDA19	Y9			
N/A	TXPPAD19	AB8			
N/A	TXNPAD19	AB7			
N/A	VTTXPAD19	AA7			
N/A	AVCCAUXTX19	AA8			
N/A	AVCCAUXRX21	AA6	NC	NC	
N/A	VTRXPAD21	AA5	NC	NC	
N/A	RXNPAD21	AB6	NC	NC	
N/A	RXPPAD21	AB5	NC	NC	
N/A	GNDA21	Y6	NC	NC	
N/A	TXPPAD21	AB4	NC	NC	
N/A	TXNPAD21	AB3	NC	NC	
N/A	VTTXPAD21	AA3	NC	NC	
N/A	AVCCAUXTX21	AA4	NC	NC	
N/A	VCCINT	U6			
N/A	VCCINT	U17			
N/A	VCCINT	T8			
N/A	VCCINT	T7			
N/A	VCCINT	T16			
N/A	VCCINT	T15			
N/A	VCCINT	R7			
N/A	VCCINT	R16			
N/A	VCCINT	H7			
N/A	VCCINT	H16			
N/A	VCCINT	G8			
N/A	VCCINT	G7			
N/A	VCCINT	G16			
N/A	VCCINT	G15			
N/A	VCCINT	F6			
N/A	VCCINT	F17			
N/A	VCCAUX	M22			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
4	IO_L54N_4	V15			
4	IO_L54P_4	W15			
4	IO_L55N_4	Y15			
4	IO_L55P_4	AA15			
4	IO_L57N_4	AB15			
4	IO_L57P_4/VREF_4	AA14			
4	IO_L67N_4	AC15			
4	IO_L67P_4	AD15			
4	IO_L69N_4	V14			
4	IO_L69P_4/VREF_4	W14			
4	IO_L74N_4/GCLK3S	AB14			
4	IO_L74P_4/GCLK2P	AC14			
4	IO_L75N_4/GCLK1S	AD14			
4	IO_L75P_4/GCLK0P	AE14			
5	IO_L75N_5/GCLK7S	AE13			
5	IO_L75P_5/GCLK6P	AD13			
5	IO_L74N_5/GCLK5S	AC13			
5	IO_L74P_5/GCLK4P	AB13			
5	IO_L69N_5/VREF_5	W13			
5	IO_L69P_5	V13			
5	IO_L67N_5	AD12			
5	IO_L67P_5	AC12			
5	IO_L57N_5/VREF_5	AA13			
5	IO_L57P_5	AB12			
5	IO_L55N_5	AA12			
5	IO_L55P_5	Y12			
5	IO_L54N_5	W12			
5	IO_L54P_5	V12			
5	IO_L53_5/No_Pair	AA11			
5	IO_L50_5/No_Pair	Y11			
5	IO_L49N_5	AD10			
5	IO_L49P_5	AC10			
5	IO_L48N_5	AB11			
5	IO_L48P_5	AB10			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R17			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U10			
N/A	GND	U12			
N/A	GND	U13			
N/A	GND	U14			
N/A	GND	U15			
N/A	GND	U17			
N/A	GND	Y20			
N/A	GND	AA21			
N/A	GND	AB22			
N/A	GND	AC23			
N/A	GND	AD24			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L53_0/No_Pair		A21	NC		
0	IO_L54N_0		H18	NC		
0	IO_L54P_0		G18	NC		
0	IO_L56N_0		C21	NC		
0	IO_L56P_0		C20	NC		
0	IO_L57N_0		J17	NC		
0	IO_L57P_0/VREF_0		H17	NC		
0	IO_L67N_0		E17			
0	IO_L67P_0		D17			
0	IO_L68N_0		D18			
0	IO_L68P_0		C18			
0	IO_L69N_0		J16			
0	IO_L69P_0/VREF_0		H16			
0	IO_L73N_0		E16			
0	IO_L73P_0		D16			
0	IO_L74N_0/GCLK7P		C16			
0	IO_L74P_0/GCLK6S		B16			
0	IO_L75N_0/GCLK5P	BREFCLKN	G16			
0	IO_L75P_0/GCLK4S	BREFCLKP	F16			
1	IO_L75N_1/GCLK3P		F15			
1	IO_L75P_1/GCLK2S		G15			
1	IO_L74N_1/GCLK1P		B15			
1	IO_L74P_1/GCLK0S		C15			
1	IO_L73N_1		D15			
1	IO_L73P_1		E15			
1	IO_L69N_1/VREF_1		H15			
1	IO_L69P_1		J15			
1	IO_L68N_1		C13			
1	IO_L68P_1		D13			
1	IO_L67N_1		D14			
1	IO_L67P_1		E14			
1	IO_L57N_1/VREF_1		H14	NC		
1	IO_L57P_1		J14	NC		
1	IO_L56N_1		C11	NC		
1	IO_L56P_1		C10	NC		

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
6	IO_L02P_6		AH26			
6	IO_L02N_6		AG26			
6	IO_L03P_6		AH29			
6	IO_L03N_6/VREF_6		AH30			
6	IO_L04P_6		AH27			
6	IO_L04N_6		AG28			
6	IO_L05P_6		AD25			
6	IO_L05N_6		AD26			
6	IO_L06P_6		AG29			
6	IO_L06N_6		AG30			
6	IO_L31P_6		AF25	NC		
6	IO_L31N_6		AE26	NC		
6	IO_L32P_6		AB23	NC		
6	IO_L32N_6		AB24	NC		
6	IO_L33P_6		AE27	NC		
6	IO_L33N_6/VREF_6		AE28	NC		
6	IO_L34P_6		AF27	NC		
6	IO_L34N_6		AF28	NC		
6	IO_L35P_6		AC25	NC		
6	IO_L35N_6		AC26	NC		
6	IO_L36P_6		AF29	NC		
6	IO_L36N_6		AF30	NC		
6	IO_L37P_6		AD27	NC		
6	IO_L37N_6		AD28	NC		
6	IO_L38P_6		AA23	NC		
6	IO_L38N_6		AA24	NC		
6	IO_L39P_6		AE29	NC		
6	IO_L39N_6/VREF_6		AE30	NC		
6	IO_L40P_6		AB25	NC		
6	IO_L40N_6		AB26	NC		
6	IO_L41P_6		Y23	NC		
6	IO_L41N_6		Y24	NC		
6	IO_L42P_6		AD29	NC		
6	IO_L42N_6		AD30	NC		
6	IO_L43P_6		AC27			
6	IO_L43N_6		AC28			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
0	IO_L43P_0	E22				
0	IO_L44N_0	E25				
0	IO_L44P_0	D25				
0	IO_L45N_0	H21				
0	IO_L45P_0/VREF_0	G21				
0	IO_L46N_0	D22				
0	IO_L46P_0	D23				
0	IO_L47N_0	D24				
0	IO_L47P_0	C24				
0	IO_L48N_0	K20				
0	IO_L48P_0	J20				
0	IO_L49N_0	F21				
0	IO_L49P_0	E21				
0	IO_L50_0/No_Pair	C21				
0	IO_L53_0/No_Pair	C22				
0	IO_L54N_0	L19				
0	IO_L54P_0	K19				
0	IO_L55N_0	G20				
0	IO_L55P_0	F20				
0	IO_L56N_0	D21				
0	IO_L56P_0	D20				
0	IO_L57N_0	J19				
0	IO_L57P_0/VREF_0	H19				
0	IO_L67N_0	G19				
0	IO_L67P_0	F19				
0	IO_L68N_0	E19				
0	IO_L68P_0	D19				
0	IO_L69N_0	L18				
0	IO_L69P_0/VREF_0	K18				
0	IO_L73N_0	G18				
0	IO_L73P_0	F18				
0	IO_L74N_0/GCLK7P	E18				
0	IO_L74P_0/GCLK6S	D18				
0	IO_L75N_0/GCLK5P	J18				
0	IO_L75P_0/GCLK4S	H18				
1	IO_L75N_1/GCLK3P	H17				
1	IO_L75P_1/GCLK2S	J17				

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
1	IO_L37N_1	G13				
1	IO_L37P_1	H13				
1	IO_L27N_1/VREF_1	J13	NC	NC		
1	IO_L27P_1	K13	NC	NC		
1	IO_L26N_1	D8	NC	NC		
1	IO_L26P_1	E8	NC	NC		
1	IO_L25N_1	F12	NC	NC		
1	IO_L25P_1	G12	NC	NC		
1	IO_L21N_1	G11	NC	NC		
1	IO_L21P_1	H11	NC	NC		
1	IO_L20N_1	C7	NC	NC		
1	IO_L20P_1	D7	NC	NC		
1	IO_L19N_1	E11	NC	NC		
1	IO_L19P_1	F11	NC	NC		
1	IO_L09N_1/VREF_1	J12				
1	IO_L09P_1	K12				
1	IO_L08N_1	D6				
1	IO_L08P_1	D5				
1	IO_L07N_1	E9				
1	IO_L07P_1	F9				
1	IO_L06N_1	J11				
1	IO_L06P_1	K11				
1	IO_L05_1/No_Pair	J10				
1	IO_L03N_1/VREF_1	G10				
1	IO_L03P_1	H10				
1	IO_L02N_1	G9				
1	IO_L02P_1	H9				
1	IO_L01N_1/VRP_1	E7				
1	IO_L01P_1/VRN_1	E6				
2	IO_L01N_2/VRP_2	D2				
2	IO_L01P_2/VRN_2	D1				
2	IO_L02N_2	F8				
2	IO_L02P_2	F7				
2	IO_L03N_2	E4				
2	IO_L03P_2	E3				
2	IO_L04N_2/VREF_2	E2				
2	IO_L04P_2	E1				

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
6	IO_L04P_6	AR33		
6	IO_L04N_6	AP33		
6	IO_L05P_6	AM32		
6	IO_L05N_6	AL31		
6	IO_L06P_6	AT34		
6	IO_L06N_6	AR34		
6	IO_L73P_6	AU35	NC	
6	IO_L73N_6	AT35	NC	
6	IO_L75P_6	AT38	NC	
6	IO_L75N_6/VREF_6	AT39	NC	
6	IO_L76P_6	AR37	NC	
6	IO_L76N_6	AR38	NC	
6	IO_L78P_6	AP38	NC	
6	IO_L78N_6	AP39	NC	
6	IO_L79P_6	AP36	NC	
6	IO_L79N_6	AP37	NC	
6	IO_L81P_6	AP35	NC	
6	IO_L81N_6/VREF_6	AN35	NC	
6	IO_L82P_6	AN38	NC	
6	IO_L82N_6	AN39	NC	
6	IO_L84P_6	AN36	NC	
6	IO_L84N_6	AN37	NC	
6	IO_L07P_6	AN33		
6	IO_L07N_6	AN34		
6	IO_L08P_6	AK31		
6	IO_L08N_6	AK32		
6	IO_L09P_6	AM37		
6	IO_L09N_6/VREF_6	AM38		
6	IO_L10P_6	AM36		
6	IO_L10N_6	AL35		
6	IO_L11P_6	AJ31		
6	IO_L11N_6	AH30		
6	IO_L12P_6	AM33		
6	IO_L12N_6	AM34		
6	IO_L13P_6	AL38		
6	IO_L13N_6	AL39		
6	IO_L14P_6	AH29		
6	IO_L14N_6	AG29		

FF1704 Flip-Chip Fine-Pitch BGA Package

As shown in Table 13, XC2VP70 and XC2VP100 Virtex-II Pro devices are available in the FF1704 flip-chip fine-pitch BGA package. Following this table are the FF1704 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
0	IO_L01N_0/VRP_0		G34		
0	IO_L01P_0/VRN_0		H34		
0	IO_L02N_0		F34		
0	IO_L02P_0		E34		
0	IO_L03N_0		C34		
0	IO_L03P_0/VREF_0		D34		
0	IO_L05_0/No_Pair		K32		
0	IO_L06N_0		H33		
0	IO_L06P_0		J33		
0	IO_L07N_0		F33		
0	IO_L07P_0		G33		
0	IO_L08N_0		E33		
0	IO_L08P_0		D33		
0	IO_L09N_0		H32		
0	IO_L09P_0/VREF_0		J32		
0	IO_L19N_0		E32		
0	IO_L19P_0		F32		
0	IO_L20N_0		C33		
0	IO_L20P_0		C32		
0	IO_L21N_0		K31		
0	IO_L21P_0		L31		
0	IO_L25N_0		H31		
0	IO_L25P_0		J31		
0	IO_L26N_0		G31		
0	IO_L26P_0		F31		
0	IO_L27N_0		D31		
0	IO_L27P_0/VREF_0		E31		
0	IO_L28N_0		L30		
0	IO_L28P_0		M30		
0	IO_L29N_0		J30		
0	IO_L29P_0		K30		
0	IO_L30N_0		G30		
0	IO_L30P_0		H30		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L27P_7		P33		
7	IO_L27N_7		P34		
7	IO_L26P_7		N31		
7	IO_L26N_7		N32		
7	IO_L25P_7		N41		
7	IO_L25N_7		N42		
7	IO_L24P_7		N39		
7	IO_L24N_7		N40		
7	IO_L23P_7		N33		
7	IO_L23N_7		N34		
7	IO_L22P_7		N37		
7	IO_L22N_7/VREF_7		N38		
7	IO_L21P_7		N35		
7	IO_L21N_7		N36		
7	IO_L20P_7		M38		
7	IO_L20N_7		M39		
7	IO_L19P_7		M40		
7	IO_L19N_7		M41		
7	IO_L18P_7		M33		
7	IO_L18N_7		M34		
7	IO_L17P_7		M31		
7	IO_L17N_7		M32		
7	IO_L16P_7		M35		
7	IO_L16N_7/VREF_7		M36		
7	IO_L15P_7		L41		
7	IO_L15N_7		L42		
7	IO_L14P_7		L39		
7	IO_L14N_7		L38		
7	IO_L13P_7		L40		
7	IO_L13N_7		K40		
7	IO_L12P_7		L36		
7	IO_L12N_7		L37		
7	IO_L11P_7		L34		
7	IO_L11N_7		L35		
7	IO_L10P_7		K42		
7	IO_L10N_7/VREF_7		K41		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		AA5		
N/A	GND		Y41		
N/A	GND		Y26		
N/A	GND		Y25		
N/A	GND		Y24		
N/A	GND		Y23		
N/A	GND		Y22		
N/A	GND		Y21		
N/A	GND		Y20		
N/A	GND		Y19		
N/A	GND		Y18		
N/A	GND		Y17		
N/A	GND		Y2		
N/A	GND		W26		
N/A	GND		W25		
N/A	GND		W24		
N/A	GND		W23		
N/A	GND		W22		
N/A	GND		W21		
N/A	GND		W20		
N/A	GND		W19		
N/A	GND		W18		
N/A	GND		W17		
N/A	GND		V37		
N/A	GND		V34		
N/A	GND		V26		
N/A	GND		V25		
N/A	GND		V24		
N/A	GND		V23		
N/A	GND		V22		
N/A	GND		V21		
N/A	GND		V20		
N/A	GND		V19		
N/A	GND		V18		
N/A	GND		V17		
N/A	GND		V9		